



## MOSFETs Silicon 800V N-Channel MOS

**■ Applications**

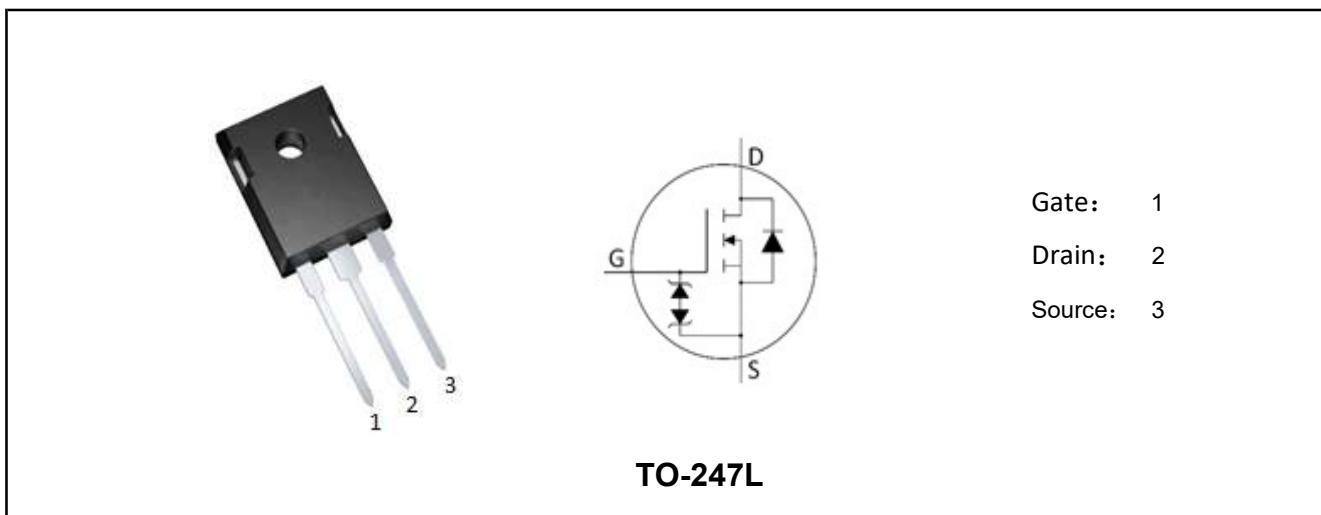
- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

**■ Features**

- Multi-Epi process SJ-FET
- Low  $R_{DS(ON)}$
- Ultra Low Gate Charge
- RoHS and Halogen-Free Compliant
- 100% UIS and RG Tested
- Fast-Recovery body diode
- Integrated Zener diode for high ESD robustness

**■ Product Summary**

$V_{DS}$ @ $T_{j,max}$	850	V
$I_D$	50	A
$R_{DS(ON),Typ}@10V$	0.094	$\Omega$
$Q_g$	95	nC



Marking	Package	Packaging	Min. package quantity
MSL110R80CFD2	TO-247L	Tube	450



**■ Absolute Maximum Ratings (Tc=25°C unless otherwise noted)**

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	800	V
Gate-Source Voltage	V <sub>GS</sub>	±30	V
Continuous Drain Current Tc=25°C (Note 1)	I <sub>D</sub>	50	A
Continuous Drain Current Tc=100°C (Note 1)		30	
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	125	A
Total Dissipation	P <sub>D</sub>	470	W
Junction Temperature	T <sub>j</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55-150	°C
Single Pulse Avalanche Energy (Note 2)	E <sub>AS</sub>	200	mJ

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

**■ Thermal Characteristics**

Parameter	Symbol	Max	Unit
Maximum Junction-to-Case	R <sub>θJC</sub>	0.27	°C/W
Maximum Junction-to-Ambient (Note 3)	R <sub>θJA</sub>	40	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: V<sub>DD</sub>=100V, T<sub>ch</sub>= 25°C(initial), L=0.5mH, I<sub>AS</sub>=25A, R<sub>g</sub>=25Ω.

Note: This transistor is sensitive to electrostatic discharge and should be handled with care.





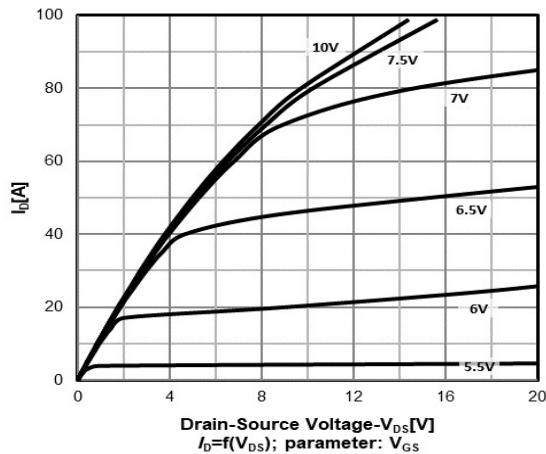
■ Electrical Characteristics (T<sub>c</sub>=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	800	-	-	V
		T <sub>j</sub> =150°C	850	-	-	
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>DS</sub> =800V, V <sub>GS</sub> =0V	-	-	5	uA
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	-	-	±1	uA
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	3	4	5	V
Drain-Source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =25A	-	0.094	0.11	Ω
		T <sub>j</sub> =150°C	-	0.22	-	
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, f=1.0MHz	-	4750	-	pF
Output Capacitance	C <sub>oss</sub>		-	2000	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	52	-	pF
Gate Resistance	R <sub>g</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1.0MHz	-	2.2	-	Ω
<b>Switching Paramters</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =25A, V <sub>GS</sub> =10V, R <sub>G</sub> =1Ω	-	27	-	ns
Turn-On Rise Time	t <sub>r</sub>		-	30	-	ns
Turn-Off Delay Time	t <sub>d(off)</sub>		-	70	-	ns
Turn-Off Fall Time	t <sub>f</sub>		-	15	-	ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =400V, I <sub>D</sub> =25A, V <sub>GS</sub> =10V	-	95	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	30	-	nC
Gate-Drain Charge	Q <sub>gd</sub>		-	30	-	nC
<b>Source-Drain Characteristics</b>						
Max. Diode Forward Cuurent	I <sub>S</sub>		-	-	50	A
Max. Pulsed Forward Cuurent	I <sub>SM</sub>		-	-	125	A
Diode Forward Voltage	V <sub>sd</sub>	V <sub>GS</sub> =0V, I <sub>S</sub> =25A	-	0.9	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> =600V, I <sub>F</sub> =25A, di/dt=100A/us	-	190	-	ns
Reverse Recovery Charge	Q <sub>rr</sub>		-	2.0	-	μC

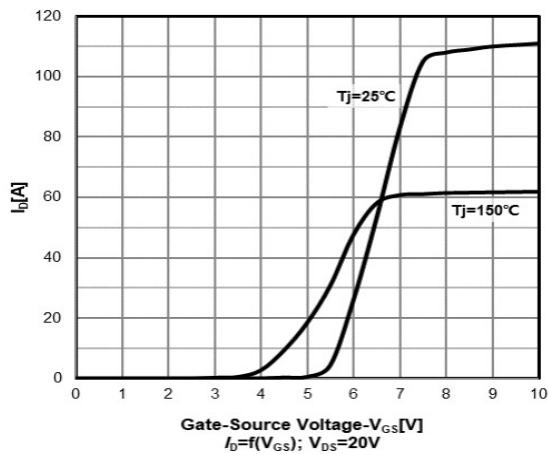




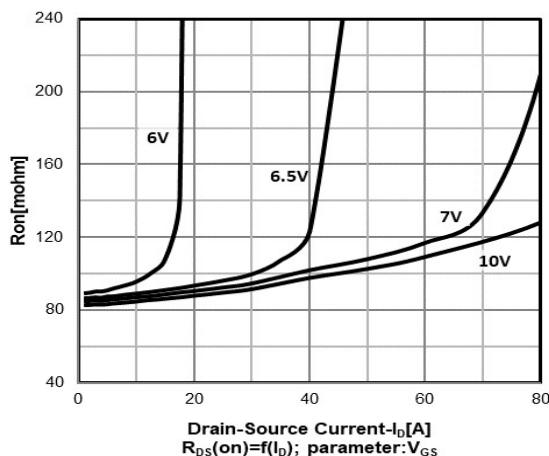
## ■ Characteristics Curves



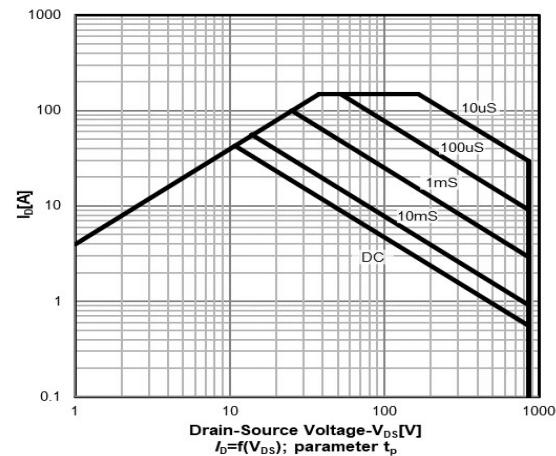
Output Characteristics



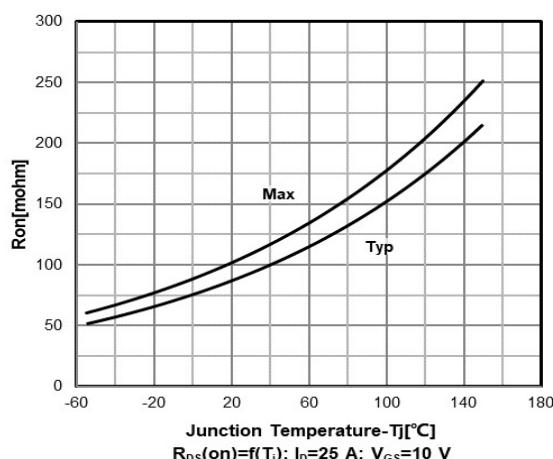
Transfer Characteristics



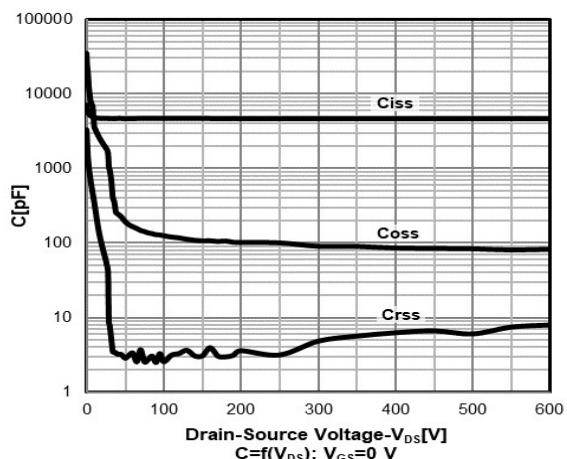
On Resistance Vs Drain Current



Maximum Safe Operating Area



Rdson-JunctionTemperature



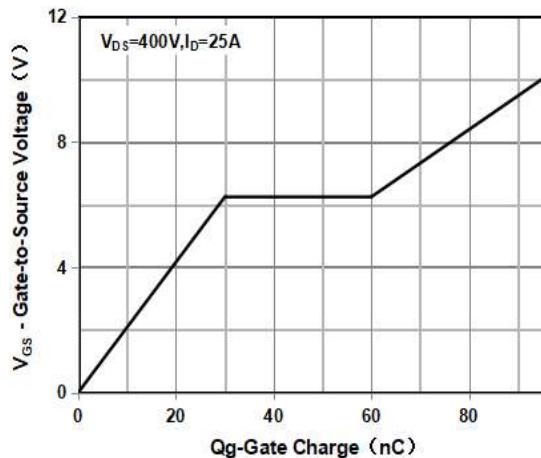
Capacitance



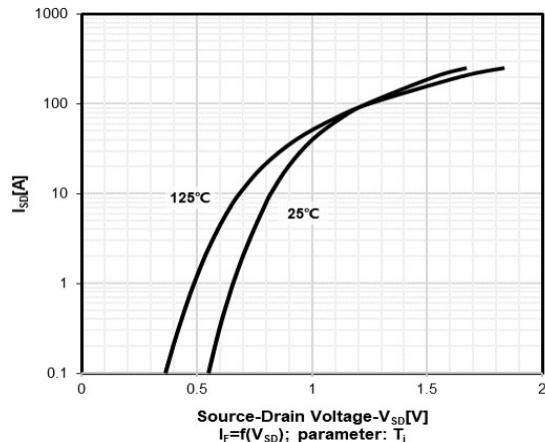


**MC-Power**

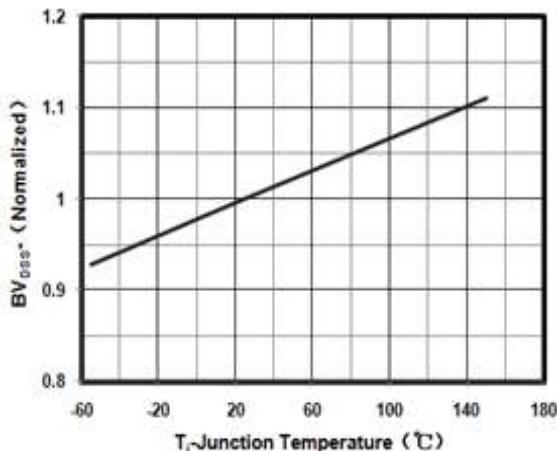
**MSL110R80CFD2**



Gate Charge Waveform



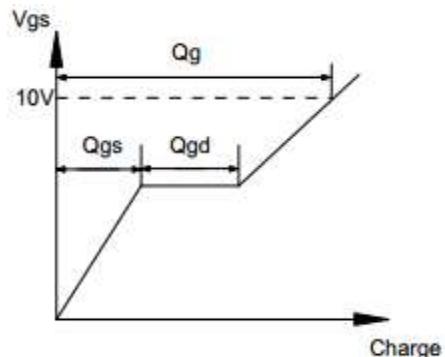
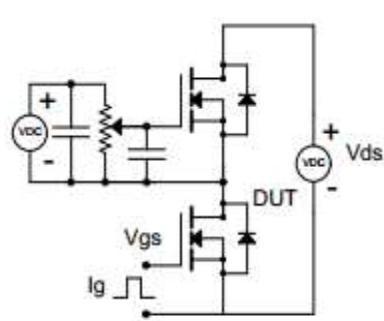
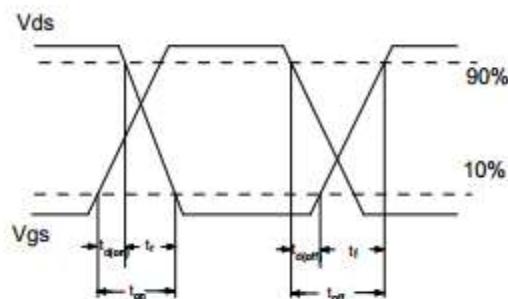
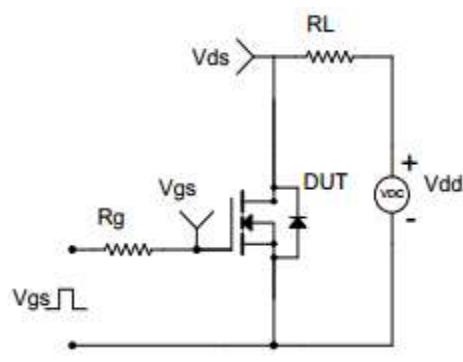
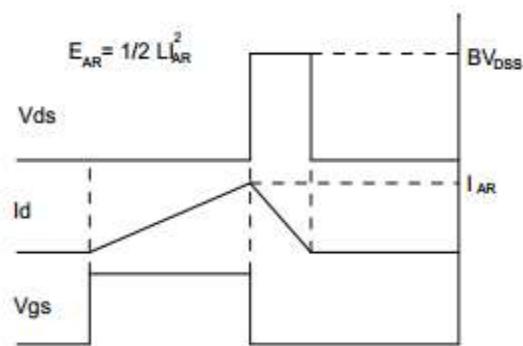
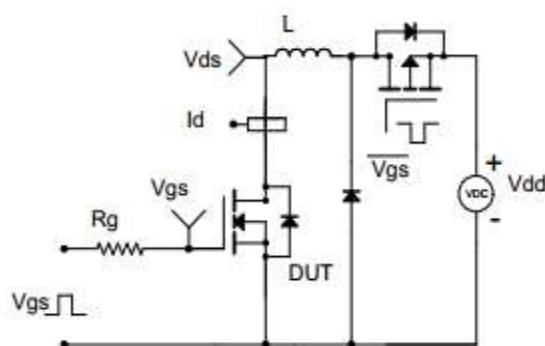
Source-Drain Diode Forward Voltage



Breakdown Voltage Vs Junction Temperature

Note : The above characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.



**■ Test Circuit & Waveform****Gate Charge Test Circuit & Waveform****Resistive Switching Test Circuit & Waveform****Unclamped Inductive Switching (UIS) Test Circuit & Waveform**



## ■ TO-247L Package Dimensions

Unit: mm

Symbol	Min	Nom	Max	Symbol	Min	Nom	Max
A	4.80		5.20	E1	13.00		13.60
A1	2.20	2.40	2.60	E2	5.00		5.50
A2	1.85		2.15	E3	1.90		2.60
b	1.07		1.33	e		5.44	
b2	1.90		2.16	L	19.30		19.90
b4	2.90		3.20	L1	3.75	3.95	4.15
c	0.52		0.68	ΦP	3.40		3.80
D	20.70		21.30	ΦP1	7.00		7.40
D1	16.15		16.95	S	6.04	6.15	6.30
E	15.50		16.10				

